PCN# : P57TAA
Issue Date : Aug. 24, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product : Nov. 22, 2015

Expected First Date Code of Changed Product :1547

Description of Change (From) :
Front-end Wafer Fabrication site Fairchild Bucheon 5-inch wafers

Description of Change (To) :
Front-end Wafer Fabrication Site Hangzhou Silan Foundry 5-inch wafers

Reason for Change:
Improve supply flexibility.
Better quality and yields through equipment and facility upgrades.
- Increased automation in handling and inspection in assembly.

Fairchild partners with foundries and assembly subcontractors.
- Best manufacturing practices, access to many customers methods and practices.
- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your companys procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	FJL6920TU	TO264	HP BJT	3

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	9/7/2015
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	10/17/2015
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	10/17/2015
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	10/11/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	9/28/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	TIP42CTU_F129	TO220	HP BJT	3

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	8/15/2015
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	9/21/2015
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	9/21/2015
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	9/10/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	8/30/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150058A	BD13916STU	TO126	HP BJT	2

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	8/16/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	9/12/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150269	FJP2160DTU	TO220	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	9/8/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	10/5/2015

Qualification Plan	Device	Package	Process	No. of Lots
Q20150269	FJD3305H1TM	TT252	HP BJT	1

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		9/10/2015
Highly Accelerated Stress Test	85%RH, 130C, 80% BV	JESD22-A110	96 hrs	9/16/2015
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	10/13/2015